



## Final Product/Process Change Notification

Document #:FPCN25614X

Issue Date: 28 Jan 2024

<b>Title of Change:</b>	TOLL SiC Leadframe, Die Attach Material, and Plasma Clean/Adhesion Promoter (AP)Coat Removal.			
<b>Proposed First Ship date:</b>	02 May 2024 or earlier if approved by customer			
<b>Contact Information:</b>	Contact your local onsemi Sales Office or <a href="mailto:Joseph.Mendoza@onsemi.com">Joseph.Mendoza@onsemi.com</a>			
<b>PCN Samples Contact:</b>	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.			
<b>Additional Reliability Data:</b>	Contact your local onsemi Sales Office or <a href="mailto:Aileen.Allado@onsemi.com">Aileen.Allado@onsemi.com</a>			
<b>Type of Notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a>			
<b>Marking of Parts/ Traceability of Change:</b>	Affected products will be identified with date code			
<b>Change Category:</b>	Assembly Change			
<b>Change Sub-Category(s):</b>	Manufacturing Process Change, Material Change			
<b>Sites Affected:</b>				
<b>onsemi Sites</b>		<b>External Foundry/Subcon Sites</b>		
onsemi Cebu, Philippines		None		
<b>Description and Purpose:</b>				
Changes in leadframe, die attach material, and pre-molding step.				
	<b>Before Change Description</b>	<b>After Change Description</b>		
<b>LeadFrame</b>	With Selective Ni/NiP plated Die Attach Pad (DAP) and leadposts	With Selective Ni plated leadposts only and bare Cu DAP		
<b>Die Attach</b>	95.5PbSn2Ag2.5 solder composition	92.5Pb5Sn2.5Ag solder composition		
<b>Pre-molding Step</b>	With Plasma Clean	None		
<b>Adhesion Promoter</b>	AP8000	None		
There is no product marking change as a result of this change.				
<b>Reliability Data Summary:</b>				
QV DEVICE NAME: NTBLO45N065SC1				
RMS: F93035				
PACKAGE: F385   CUST8 AL SNGL HPBF				
<b>Test</b>	<b>Specification</b>	<b>Condition</b>	<b>Interval</b>	<b>Results</b>
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C, Pre TC, uHAST, for surface mount pkgs only		0/462
Temperature Cycling	JESD22-A104	Ta= -55°C to + 150°C	1000 cyc	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231



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### Electrical Characteristics Summary:

Electrical characteristics are not impacted.

### List of Affected Parts:

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
NTBL045N065SC1	NTBL045N065SC1